

## Custom Assembly

March 2007

### Backplanes

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Dimensions up to 48" x 30"	Press-fit (compliant –pin)	AOI & X-ray inspection
Thickness up to .400"	Surface mount (chip, QFP, BGA)	Level 2, 3 & 4 testing
Custom and Industry Standard	Wave / selective solder	Conformal coating

### Flex & Rigid-Flex

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Dimensions up to 24" x 36"	Press-fit (compliant-pin)	AOI & X-ray inspection
Passive & active components	Surface mount (chip, QFP, BGA)	Level 2,3, & 4 testing

### RF / Microwave

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Dimensions up to 24" x 36"	1-piece hermetic GPO and GPPO	X-ray inspection
Blind via, surface mount, thru-hole		RF testing (20+ GHz)

### Integrated Assembly

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Card cage through cabinet	Power supplies / fan trays	Functional testing
Backplanes / midplanes	Peripherals & controllers	Mil / Aero conduction cooled
Harnessing / cabling	I/O interfaces	

### Approvals & Qualifications

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ISO 9000 (Quality System)	UL Recognized	MIL-A-28870 (QML)
ISO 14000 (Environmental)	IPC-A-600, Class 3 (inspection)	MIL-STD-2166 (compliant pin)
AS9100 (Aerospace)	IPC-7711 (rework)	RoHS compliant
TL 9000 (Telecom)	J-STD-001, Class 3 (workmanship)	

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